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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/687,112	10/15/2003	Bioh Kim	SEMT116964	7221
26389 7590 10/09/2008 CHRISTENSEN, O'CONNOR, JOHNSON, KINDNESS, PLLC 1420 FIFTH AVENUE SUITE 2800 SEATTLE, WA 98101-2347				
EXAMINER TALBOT, BRIAN K				
ART UNIT		PAPER NUMBER		
1792				
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10/09/2008		PAPER		

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary

Application No.

10/687,112

Applicant(s)

KIM, BIOH

Examiner

Brian K. Talbot

Art Unit

1792

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --
Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 23 July 2008.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-26 and 42 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-26 and 42 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- 1) ☒ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO/CDC)
- 4) ☐ Interview Summary (PTO-413)
- 5) ☐ Notice of Informal Patent Application
- 6) ☐ Other: _____
- Paper No(s)/Mail Date _____

1. The amendment filed 7/23/08 has been considered and entered. Claims 27-41 have been canceled. Claim 42 has been added. Claims 1-26 and 42 remain in the application.
2. The text of those sections of Title 35, U.S. Code not included in this action can be found in a prior Office action.
3. In light of the amendment filed 7/23/08, the 35 USC 103 rejections have been withdrawn. However, the following rejection has been necessitated by the amendment.

Claim Rejections - 35 USC § 103

4. Claims 1-26 and 42 are rejected under 35 U.S.C. 103(a) as being unpatentable over in Hur et al. (6,013,572) combination with Mis et al. (6,762,122) or Jan et al. (7,081,404) further in combination with Batinovich (2004/0040855).

Hur et al. (6,013,572) teaches a method of fabricating and testing silver-tin alloy solder bumps. A masked underbump metallurgy layer on a microelectronic substrate defining exposed portions of the underbump metallurgy layer is plated with silver, then plated with tin and then reflowed to form the silver-tin alloy bump (abstract and col. 1, line 55 – col. 2, line 12). The silver and tin layers are applied by electroplating (col. 2, lines 28-42). In another embodiment, two layers of silver and plated followed by a layer of tin and reflowing is performed (col. 2, lines 53-62). The first underbump metallurgy layer is Ti, Cr or TiW. The second underbump metallurgy layer is copper or nickel (col. 2, lines 19-27). The tin layer can comprise an alloy such as silver-tin (col. 3, lines 1-3). The first underbump layer is considered a barrier layer by

the Examiner as it comprises Cr, Ti or TiW which are conventional barrier/diffusion layers in the art.

Hur et al. (6,013,572) fails to teach forming a diffusion barrier layer on the UBM layer underneath the solder material.

Mis et al. (6,762,122) teaches method of forming metallurgy structures for wire and solder bonding. An under bump metallurgy (27) can include barrier layer and conductor layers. On top of the UBM layer is applied barrier layers (31a-31d) and capping layers (33a-33d) (col. 3, line 37 – col. 4, line 50 and Figs. 1A-1C and 2A-2C)

Jan et al. (7,081,404) teaches method of selectively bumping integrated circuit substrates whereby a first barrier layer (27) is formed, then a UBM layer (29) is formed and then a second barrier layer (320) is formed prior to forming the solder bump (35) (col. 4, line 65 - col. 5, line 52 and Figs. 1-8).

Therefore it would have been obvious for one skilled in the art at the time the invention was made to have modified Hur et al. (6,013,572) solder bump process by incorporating a barrier/diffusion layer above the UBM layer and beneath the solder material as evidenced by Mis et al. (6,762,122) or Jan et al. (7,081,404) with the benefits associated with such a layer as detailed above.

Hur et al. (6,013,572) in combination with Mis et al. (6,762,122) or Jan et al. (7,081,404) fail to teach the UBM layer comprising a barrier layer and a seed layer.

Batinovich (2004/0040855) teaches a method for low-cost underbump metallization for flip chip and BGA's. Batinovich (2004/0040855) teaches a UBM comprising an adhesion/barrier layer of titanium/tungsten alloy and a wettable layer comprising copper or

nickel. Batinovich (2004/0040855) further teaches that a seed layer can be applied between the adhesion/barrier layer and wettable layer ([0032] and Figs. 1a-1d).

Therefore it would have been obvious for one skilled in the art at the time the invention was made to have modified Hur et al. (6,013,572) in combination with Mis et al. (6,762,122) or Jan et al. (7,081,404) UBM layer to include a adhesion/barrier layer and seed layer as evidenced by Batinovich (2004/0040855) with the expectation of achieving similar success.

Response to Amendment

5. Applicant's arguments filed 7/23/08 have been fully considered but they are not persuasive.

Applicant argued that the Hur et al. (6,013,572) in combination with Mitchell et al. (5,773,359) fails to teach a UBM layer comprising a barrier layer and a seed layer and forming a second barrier layer atop the UBM layer.

Mis et al. (6,762,122) or Jan et al. (7,081,404) teaches this limitation as noted above.

6. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Brian K. Talbot whose telephone number is (571) 272-1428. The examiner can normally be reached on Monday-Friday 8AM-4PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Timothy H. Meeks can be reached on (571) 272-1423. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

//Brian K Talbot//
Primary Examiner, Art Unit 1792

BKT